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Part Number: [0712515101](#)
Status: **Active**
Description: 1.27mm (.050") Pitch DIMM Socket, Vertical, Multiple Keys, Plastic Peg, 100 Circuits, 3.3V Unbuffered

Documents:
[3D Model](#) [Product Specification PS-71243-9999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Memory Module Sockets
Series [71251](#)
Comments Function Key Offset Right, Voltage Key Center
Component Type Memory Module
JEDEC Outline MO-161
Product Name DIMM

Physical

Circuits (Loaded) 100
Color - Resin Black, Natural
Durability (mating cycles max) 25
Entry Angle Vertical (Top Entry)
Flammability 94V-0
Function Key Offset Right
Keying to Mating Part Yes
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
PCB Retention Yes
Packaging Type Tray
Pitch - Mating Interface (in) 0.050 In
Pitch - Mating Interface (mm) 1.27 mm
Plating min: Mating (µin) 2
Plating min: Mating (µm) 0.05
Plating min: Termination (µin) 150
Plating min: Termination (µm) 3.81
Temperature Range - Operating -40°C to +85°C
Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1A
Voltage - Maximum 100V
Voltage Key Center

Solder Process Data

Duration at Max. Process Temperature (seconds) 40
Lead-free Process Capability Wave Capable (TH only)
Max. Cycles at Max. Process Temperature 3
Process Temperature max. C 260

Material Info

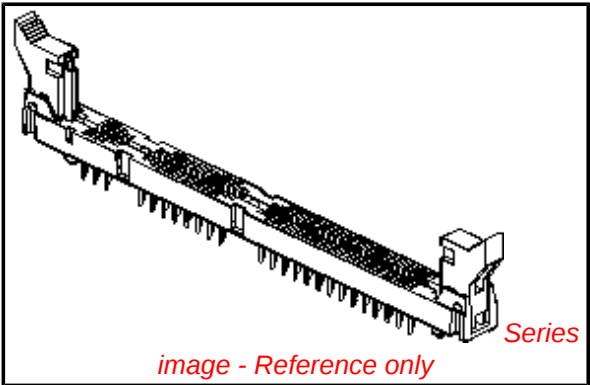


image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Halogen-Free

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[71251Series](#)

Mates With
JEDEC MO-161 modules

Reference - Drawing Numbers

Product Specification
Sales Drawing

PS-71243-9999
SD-71251-5101, SDA-71251-5***

This document was generated on 04/13/2010

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注記
NOTES:

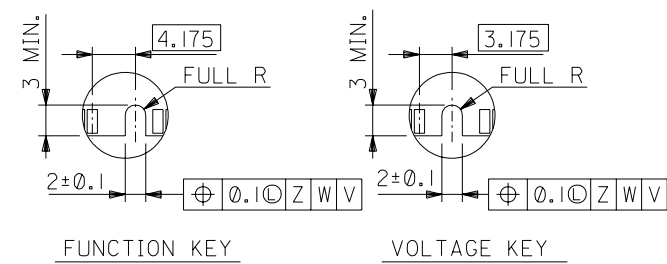
7. 製造日コードはハウジングの側面に刻印されます。
PRODUCT WILL HAVE DATE CODE
STAMPED ON SIDE OF HOUSING.
8. 材質
ハウジング：耐熱性樹脂（黒色）
ラッチ：耐熱性樹脂（アイボリー）
ターミナル：リン青銅
- MATERIALS:
HOUSING- HIGH-TEMP THERMOPLASTIC
COLOR: BLACK
LATCHES - HIGH-TEMP THERMOPLASTIC
COLOR: IVORY
TERMINAL- PHOSPHOR BRONZE
9. メッキ仕様
接点部：金メッキ 0.05-0.25MICROMETER
パラジウムニッケル下地 0.76MICROMETER MIN.
半田付け部：錫メッキ 3.81MICROMETER MIN.
下地メッキ：ニッケルメッキ 1.27MICROMETER MIN.
PLATING:
CONTACT AREA: GOLD 0.05-0.25MICROMETER
OVER PALLADIUM-NICKEL

SOLDER TAILS: TIN
3.8 MICROMETER MIN.
UNDERPLATE: NICKEL 1.27 MICROMETER MIN.

⑩ モジュール基板の真直度は、底辺より4mmの範囲に適用。
STRAIGHTNESS OF MODULE APPLIES TO
THE AREA FROM THE BOTTOM OF THE
CARD UP 4.

11. 電解メッキなどのために、パッドにタブを設ける場合は、それがコネクタのコンタクト部を損傷する原因とならないよう、ご配慮下さい。

IF TIE BARS ARE ATTACHED TO PADS,
THE TIE BAR SHOULD BE ON AN INTERNAL
LAYER, SO THAT THE REMNANT CANNOT
CAUSE DAMAGE TO THE CONTACTS.



基板推奨寸法

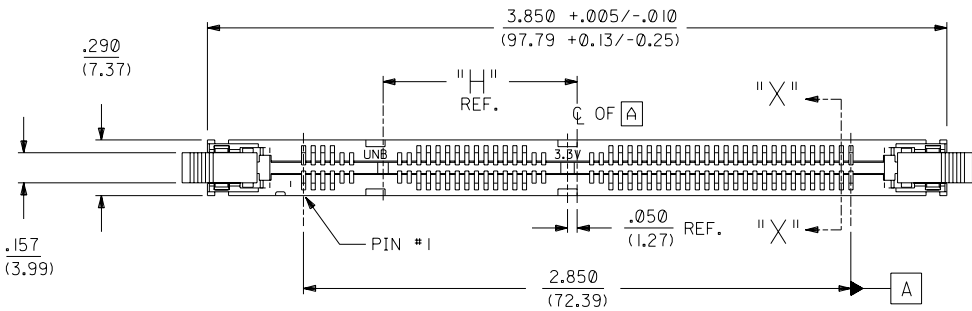
RECOMMENDED P.C.B. LAYOUT

角度 ANGLE	$\pm 3^{\circ}$				
30 以上 OVER	± 0.3				
10 以上 OVER 30 未満 UNDER	± 0.25	A			
10 未満 UNDER	± 0.2	0	SHEET 1 OF 2 参照 SEE SHEET 1 OF 2		
般公華 GENERAL OF FRANCES	記号 R	変更内容 REVISION RECORD	DR.	CHK	日付 DATE

材料 MATERIAL	注参照 SEE NOTES		 MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
仕上げ FINISH	注参照 SEE NOTES		
適用電線範囲 WIRE RANGE	— # —		TITLE 名称 1.27 PITCH DIMM 100 CIRCUIT MULTI-KEY HOUSING ASS'Y -LEAD FREE-
被覆外径 INS. RANGE	— # —		DWG. NO. SHEET 2 OF 2 RE
DRAWN BY '98/11/12 <i>T. Kinta</i>	CHK'D BY <i>H. Sato</i>		
APP'D BY 	尺度 SCALE 2 - 1		SD-71251-5101 A

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EN-0 IC(032)MXJ-32



NOTES:

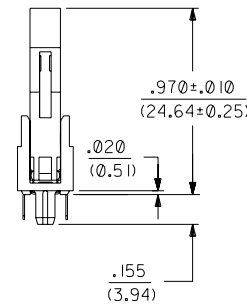
1. CARD SLOT ACCEPTS $.050 \pm .004$ (1.27 $\pm$.10) MODULE THICKNESS. (MEASURED OVER P.C. PADS).
2. ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.
3. REFER TO PRODUCT SPEC. PS-71243 FOR PERFORMANCE SPECIFICATIONS.
4. PRODUCT IS PACKAGED IN TRAYS.
5. RECOMMENDED MODULE LAYOUT SHALL BE PER MO-161.
6. RECOMMENDED PLATING ON MODULE PADS: 30 MICROINCH/(0.76 MICROMETER) MINIMUM HARD GOLD (Au) OVER 79 MICROINCH/(2.0 MICROMETER) MINIMUM NICKEL (Ni).
7. PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

MATERIALS:

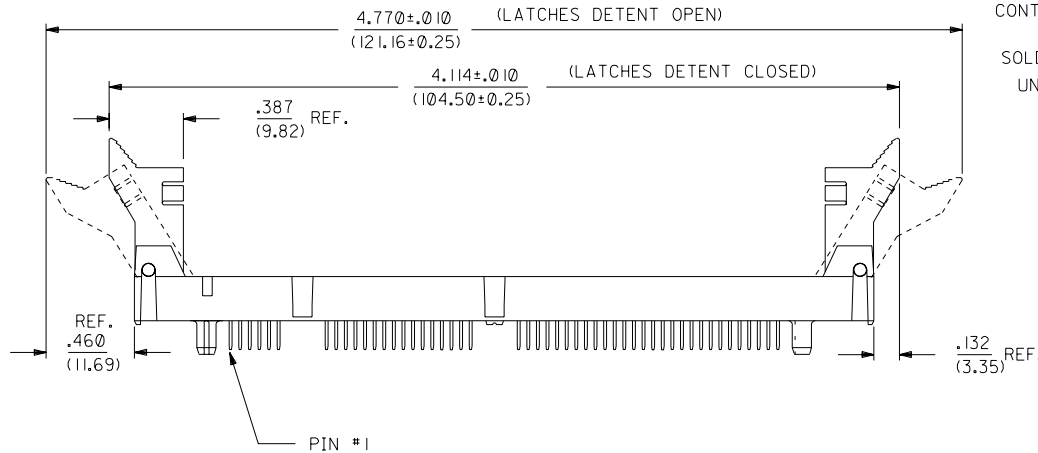
HOUSING - GLASS FILLED LIQUID CRYSTAL POLYMER (LCP), UL 94V-0, COLOR: BLACK.
 TERMINAL - PHOSPHOR BRONZE
 LATCHES - GLASS FILLED HIGH TEMPERATURE NYLON, UL 94V-0, COLOR: IVORY.

PLATING:

CONTACT AREA: MOLEX EBI LUBRICANT OVER
 GOLD (Au): THICKNESS=10 MICROINCH/(0.25 MICROMETER) MINIMUM.
 SOLDER TAILS: TIN (Sn): THICKNESS=150 MICROINCH/(3.81 MICROMETER) MINIMUM.
 UNDERPLATE: NICKEL (Ni) OVER ENTIRE CONTACT.



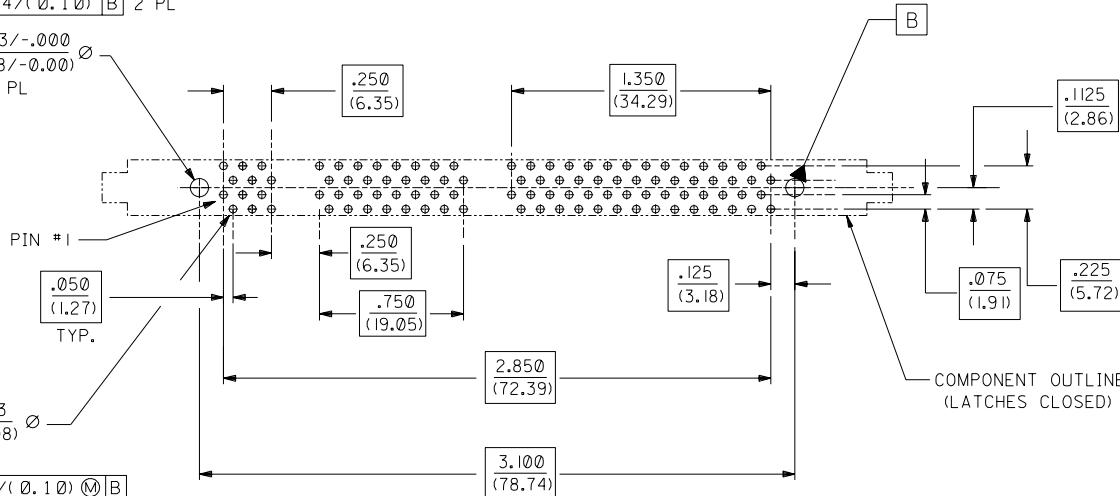
NOTE FOR LEAD FREE CONVERSION:
 THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.



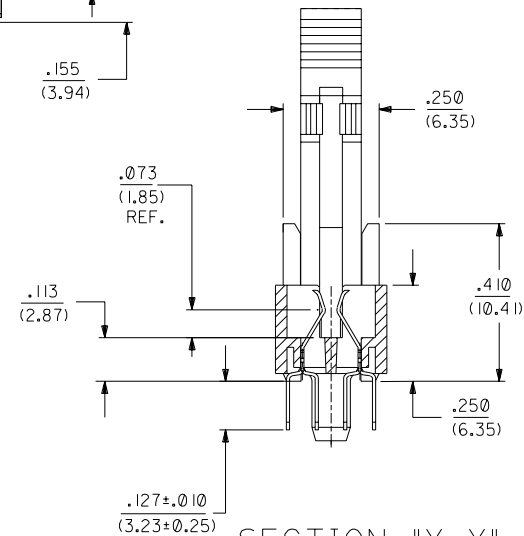
71251-5101 SHOWN

$\varnothing .004 / (0.10)$ B 2 PL

$.093 + .003 / -.000$
 (2.36 +0.08/-0.00) $\varnothing$
 2 PL



RECOMMENDED
 P.C. BOARD HOLE PATTERN
 (CONNECTOR SIDE)



SECTION "X-X"

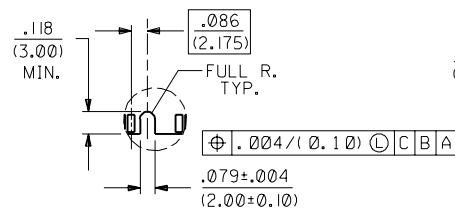
SCALE 4:1

C1	ADD LEAD FREE NOTE ECN# UC2004-1732 DMORGAN 04/03/09
C	CHANGE PLATING ECN# UDT2002-0712 DMORGAN 02/01/22
B	CHG Sn-Pb THICKNESS ECN# UDT1999-0454 DMORGAN 99/08/09
A1	REVISED PER ECR# U80435 97-8-8 LAURX
A	REVISED PER ECR# U70042 96-7-23 LAURX
2	REVISED PER ECR# U61257 4-10-96 JCL
	X-RELEASE PER ECR# U61175 3-26-96 JCL

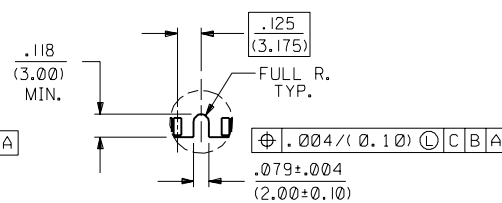
DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR $\pm 1/2^\circ$		TITLE 71251-5101 0.050 PITCH DIMM 100 CKT MULTI-KEY SALES DRAWING		SHEET NO. 1 OF 2		DATE 03/26/96	
3 PLACE $\pm .005$	INCH	2 PLACE $\pm .01$	METRIC	1 PLACE $\pm .025$	INCH	2 PLACE $\pm .01$	METRIC
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				REVISE ONLY ON CAD SYSTEM			
DRWG. BY JCL		CHK'D. BY DCB		SCALE 2:1		FILE NAME ST125151.DGN	
APPROV. BY DCB		SCALE 2:1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DIV. CP	

13		12		11		10		9		8		7		6		71251		4		3		2		1	
PART NUMBER		DESCRIPTION		FUNCTION KEY		VOLTAGE KEY		DIM. "H"																	
71251-5101		3.3 VOLT UNBUFFERED		OFFSET RIGHT		CENTER		1.011 (25.68)																	
71251-5102		5.0 VOLT UNBUFFERED		OFFSET RIGHT		OFFSET LEFT		1.011 (25.68)																	

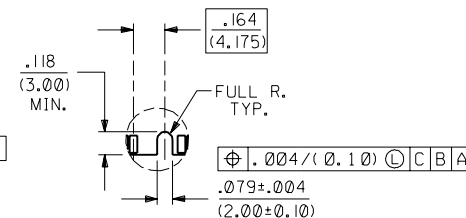
- NOTES:
1. STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP .157/(4.00).
 2. IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.



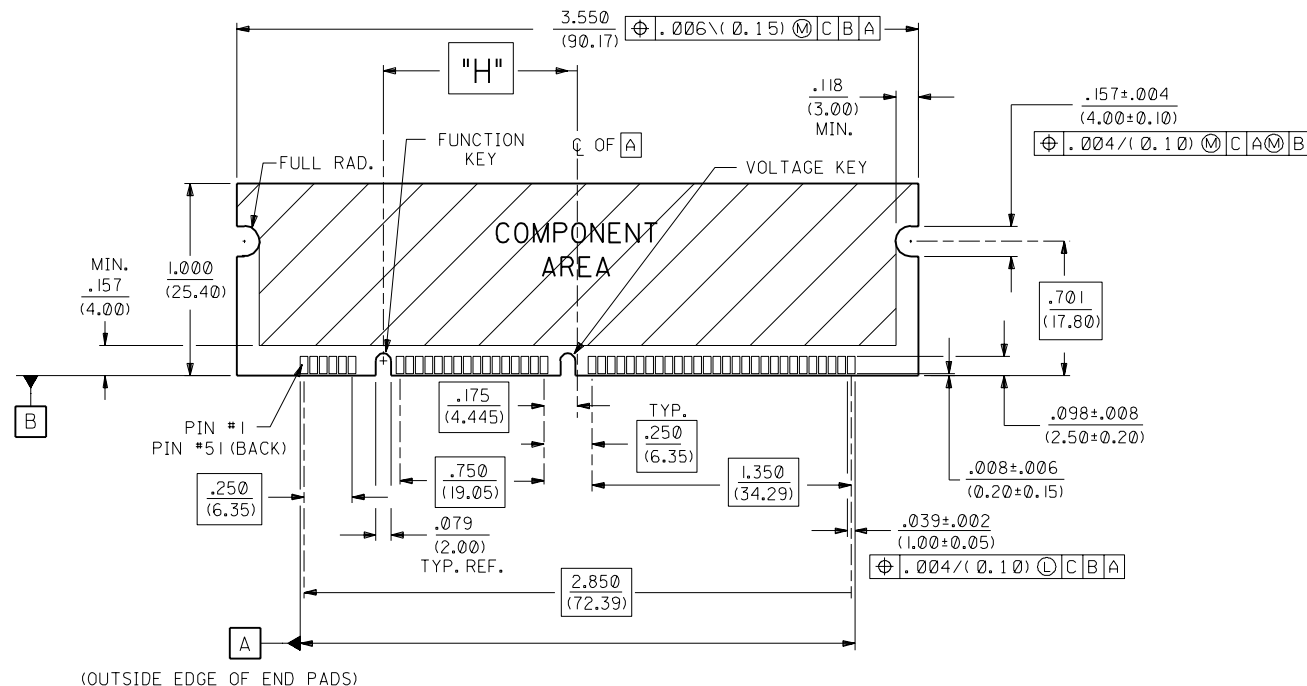
OFFSET LEFT KEY



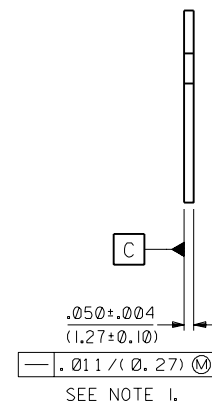
CENTERED KEY



OFFSET RIGHT KEY



RECOMMENDED MODULE LAYOUT
100 CKT 3.3V UNBUFFERED



MFG.	SH.	REV.	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES ANGULAR ± 1/2°		TITLE 050 PITCH DIMM 100 CKT MULTI-KEY SALES DRAWING	
3 PLACE ± .005	INCH	2	SHEET NO.
2 PLACE ± .01	METRIC	2	DATE
1 PLACE --- ± 0.25		2	03/26/96
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
DRWG. BY: JCL	CHK'D BY: DCB	FILE NAME: 5725152.DWG	DIV. CP
APP'D BY: DCB	SCALE: 2: 1	REVISE ONLY ON CAD SYSTEM	

13		12		11		10		9		8		7		6		5		4		3		2		1	
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